

1     What is claimed is:

2     1. A thin type BGA semiconductor package comprising:

3         a composite substrate including a wiring board and a dummy die, wherein the wiring  
4         board has an upper surface, a lower surface and an opening, the opening passes  
5         through the upper surface and the lower surface, a step is formed in the opening, a  
6         plurality of ball pads are formed on the lower surface, a plurality of connecting pads  
7         are formed on the step and electrically connect with the ball pads, the dummy die is  
8         attached to the lower surface of the wiring board and covers the opening to form a  
9         chip cavity;

10        an integrated circuit chip disposed in the chip cavity, the chip having an active  
11        surface and a back surface, a plurality of bonding pads being formed on the active  
12        surface and electrically connected to the connecting pads of the wiring board, the  
13        back surface of the chip being attached to the dummy die;

14        a package body formed in the chip cavity of the composite substrate; and

15        a plurality of solder balls on the ball pads.

16     2. The package of claim 1, wherein the dummy die has a thickness smaller than the  
17         diameter of the solder balls.

18     3. The package of claim 1, wherein the dummy die has an exposed surface without  
19         attaching the wiring board, a metal film is formed on the exposed surface.

20     4. The package of claim 1, wherein the wiring board has a plurality of ball-stacking pads  
21         formed on the upper surface of the wiring board.

22     5. A thin type semiconductor package comprising:

23         a composite substrate including a wiring board and a dummy die, wherein the wiring  
24         board has an upper surface, a lower surface and an opening, the opening passes  
25         through the upper surface and the lower surface, a plurality of ball pads are formed on  
26         the lower surface, a plurality of connecting pads are formed around the opening and  
27         electrically connect with the ball pads, the dummy die is attached to the lower surface

- 1 of the wiring board and covers the opening to form a chip cavity;  
2 an integrated circuit chip disposed in the chip cavity, the chip having an active  
3 surface and a back surface, a plurality of bonding pads being formed on the active  
4 surface and electrically connected to the connecting pads of the wiring board, the  
5 back surface of the chip being attached to the dummy die; and  
6 a package body formed in the chip cavity of the composite substrate.
- 7 6. The package of claim 5, wherein the dummy die has an exposed surface without  
8 attaching the wiring board, a metal film is formed on the exposed surface.
- 9 7. The package of claim 5, further comprising a thermosetting compound mechanically  
10 bonding the dummy die and the wiring board.
- 11 8. A thin type semiconductor package comprising:  
12 a composite substrate including a wiring board and a dummy die, wherein the wiring  
13 board has an upper surface, a lower surface and an opening, the opening passes  
14 through the upper surface and the lower surface, a plurality of ball pads are formed on  
15 the lower surface, a plurality of connecting pads are formed around the opening and  
16 electrically connect with the ball pads, the dummy die has a first surface and a second  
17 surface, the first surface of the dummy die includes a central region and a peripheral  
18 region surrounding the central region, the peripheral region of the dummy die is  
19 attached to the lower surface of the wiring board;  
20 an integrated circuit chip having an active surface and a back surface, a plurality of  
21 bonding pads being formed on the active surface, the back surface being attached to  
22 the central region of the dummy die;  
23 a plurality of bonding wires connecting the bonding pads of the chip with the  
24 connecting pads of the wiring board; and  
25 a package body formed in the opening of the wiring board and sealing the chip and  
26 the bonding wires.
- 27 9. The package of claim 8, wherein the package body is a dispensing material.

- 1 10. The package of claim 8, wherein the dummy die has a thickness smaller than the  
2 diameter of the solder balls.
- 3 11. The package of claim 8, wherein the dummy die has a metal film being formed on the  
4 second surface thereof.
- 5 12. The package of claim 8, wherein the wiring board has a plurality of ball-stacking pads  
6 on the upper surface of the wiring board.
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